



PK916(v1.0) June 22, 2017

100% Material Declaration Data Sheet for Zynq UltraScale+ SBVA/SBVC484

Average Weight : 1.6240 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die	Silicon	7440-21-3	100.00	basis	0.166118	10.229%
					0.166118	
Bump	Tin	7440-31-5	98.20	basis	0.007168	0.441%
	Silver	7440-22-4	1.80	basis	0.000129	
					0.000129	
Underfill	Bisphenol F type liquid	9003-36-5	15.00	basis	0.004200	1.724%
	1,6-Bis(2,3-	27610-48-6	10.00	basis	0.002800	
	Bisphenol A type liquid	25068-38-6	5.00	basis	0.001400	
	Amine type hardener	trade secret	10.00	basis	0.002800	
	Silicon dioxide	60676-86-0	58.00	filler	0.016240	
	Carbon black	1333-86-4	1.00	color agent	0.000280	
	Additives	trade secret	1.00	additives	0.000280	
					0.000280	
Solder ball	Tin	7440-31-5	96.50	metal	0.225791	14.408%
	Silver	7440-22-4	3.00	metal	0.007019	
	Copper	7440-50-8	0.50	metal	0.001170	
					0.001170	
Substrate	Copper	7440-50-8	55.11		1.188734	73.198%
	Tin	7440-31-5	0.62		0.655177	
	Silver	7440-22-4	0.02		0.007370	
	Resin	N/A	0.29		0.000238	
	Core	N/A	30.37		0.003447	
	ABF	N/A	11.96		0.360953	
	Solder Mask	N/A	1.63		0.142173	
					0.019376	

Revision History

Date	Version	Description of Revisions
6/22/2017	1.0	Initial Xilinx Release.

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